

ABSTRACT OF THE DISCLOSURE

A thermally conductive substrate includes a thermally conductive resin sheet member attached to a lead frame. The lead frame comprises a thermally conductive resin sheet member and it is integrated with the thermally conductive resin sheet member on the lead frame. The thermally conductive resin sheet member is formed from a thermosetting resin mixture which comprises 70 to 90 parts by weight of an inorganic filler and 5 to 30 parts by weight of a thermosetting resin composition including a thermosetting resin, and the thermosetting resin is in a semi-cured state.